PacTech USA will complete construction of its 2000 ft2 clean room

PacTech USA Packaging Technologies, Inc. located in Santa Clara, CA will complete construction of its 2000 ft2 clean room by November 2002. According to Ron Blankenhorn, President of PacTech USA, this facility will serve to demonstrate Pac Tech Germany designed and built production and prototype equipment.
Dr. Thorsten Teutsch, the new CTO of PacTech USA, says that Pac Tech USA already accepts orders for Electroless Ni/Au under-bump metalization process using our parent company, Pac Tech Germany; he will direct the transfer this same process to Pac Tech USA. Dr. Teutsch states that the new PacLine 2000 A 50 being installed is capable of a volume wafer bumping capacity of 600,000 200mm equivalents per year and is 300mm capable. ISO 9001 certification of the process is scheduled for Q3/2003 according to Dr. Teutsch.

By September, PacTech USA will begin operating a showroom and application laboratory for local demonstration of solder balling services using PacTech´s Solder Ball Bumper SB2. This unique machine is capable to perform a fluxless solder jetting process (10 balls/sec). Beside fast prototyping and repair features the SB2 is the ultimate solution for solder bumping of FlipChip, BGA, MEMs, HDD, and Optical Devices.